

Serial No. 10/796,360

In the Claims:

Please amend the claims as follows:

1. (currently amended) A light emitting diode assembly comprising:
a prepackaged light emitting diode assembly including:
having a front luminescent portion, and
a mounting base, said mounting base having a heat transfer plate on a rear surface thereof and a first and second contact lead extending from the sides thereof;
a mounting die, said mounting die being thermally conductive, said mounting die having a bottom surface and a side wall extending upwardly from said bottom surface, said bottom surface and said side wall cooperating to form a cavity therein, wherein said prepackaged light emitting diode assembly is received in said cavity with said heat transfer plate in thermal communication with said bottom surface of said mounting die.
2. (currently amended) The light emitting diode assembly of claim 1, wherein said second first contact lead of said prepackaged light emitting diode assembly is in electrical communication with said mounting die.
3. (currently amended) The light emitting diode assembly of claim 1, further comprising:
a void hole in said rear surface of said mounting die corresponding to said first second contact lead of said light emitting diode disposed to prevent said first second contact lead of said prepackaged light emitting diode assembly from contacting said mounting die.
4. (currently amended) The light emitting diode assembly of claim 3, wherein said second first contact lead of said prepackaged light emitting diode assembly is in electrical communication with said mounting die.
~~a void in said rear surface of said mounting die corresponding to said first contact lead of said light emitting diode disposed to prevent said first contact lead of said light emitting diode from contacting said mounting die.~~

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5. (currently amended) The light emitting diode assembly of claim 4, further comprising:

a circuit board adjacent to said mounting die, said circuit board in electrical communication with said ~~first~~ second contact lead of said prepackaged light emitting diode assembly.

6. (currently amended) The light emitting diode assembly of claim 5, further comprising:

means for fastening said prepackaged light emitting diode assembly, said mounting die and said circuit board to form a single assembly.

7. (currently amended) A heat sink assembly for mounting a prepackaged light emitting diode assembly comprising:

a mounting die, said mounting die having a bottom wall and a side wall extending upwardly from said bottom wall, said side wall and said bottom wall cooperating to form an interior cavity, said interior cavity being configured to receive a prepackaged light emitting diode assembly, wherein a luminescent portion of said prepackaged light emitting diode assembly directs light output outwardly from said cavity; and

means for conducting heat from said prepackaged light emitting diode assembly to said mounting die.

8. (currently amended) The heat sink assembly of claim 7, wherein said means for conducting heat is a heat transfer plate on a rear surface of said prepackaged light emitting diode assembly, said heat transfer plate being in thermal communication with said bottom wall of said mounting die.

9. (currently amended) The light emitting diode assembly of claim 7, further comprising:

means for fastening said prepackaged light emitting diode assembly to said mounting die to form a single assembly.

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10. (currently amended) A flashlight assembly comprising:
at least one battery, said battery having a first and second electrical contact,
said first contact;
a flashlight head assembly connected to said at least one battery and including,
a prepackaged light emitting diode assembly having a front luminescent
portion and a rear mounting base, said mounting base having a heat transfer
plate on a rear surface thereof and a first and second contact lead extending
from the sides thereof,
a mounting die, said mounting die being thermally conductive, said
mounting die having a bottom surface and a side wall extending upwardly from
said bottom surface, said bottom surface and said side wall cooperating to form a
cavity therein, wherein said prepackaged light emitting diode assembly is
received in said cavity with said heat transfer plate in thermal communication
with said bottom surface of said mounting die, wherein said mounting die
conducts heat away from said light emitting diode,
an exterior enclosure; and
means for selectively energizing said prepackaged light emitting diode
assembly disposed between and in electrical communication with said first and second
contacts of said battery and said first and second contacts on said prepackaged light
emitting diode assembly.